



深圳市凯越翔电子有限公司

声表谐振器规格书

产品名称:	声表谐振器
产品型号:	T0-39/433.92M
产品参数:	±75KHZ
原厂型号:	KT043392
凯越翔技术部:	董宗全

客户确认栏

认证印章 年 月 日	负责人印章 年 月 日
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1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with used for remote-control security.

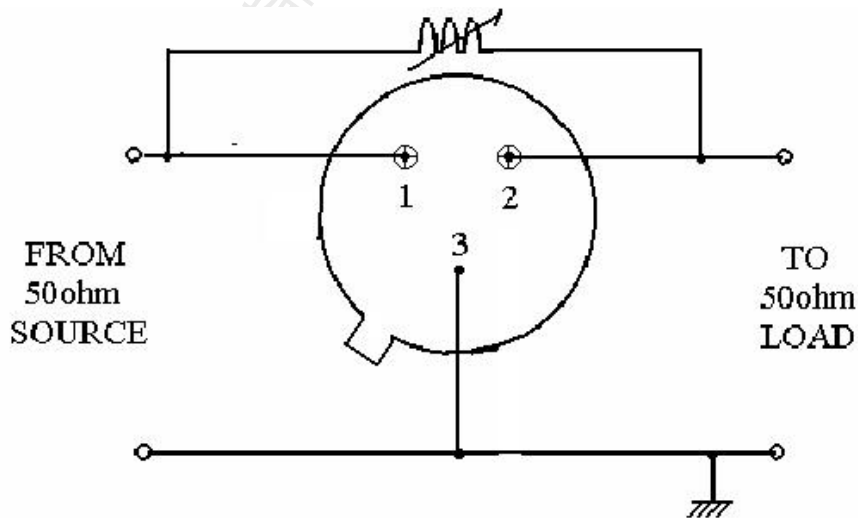
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-20°C to +70°C
Storage temperature	-40°C to +85°C
RF Power Dissipation	0dBm

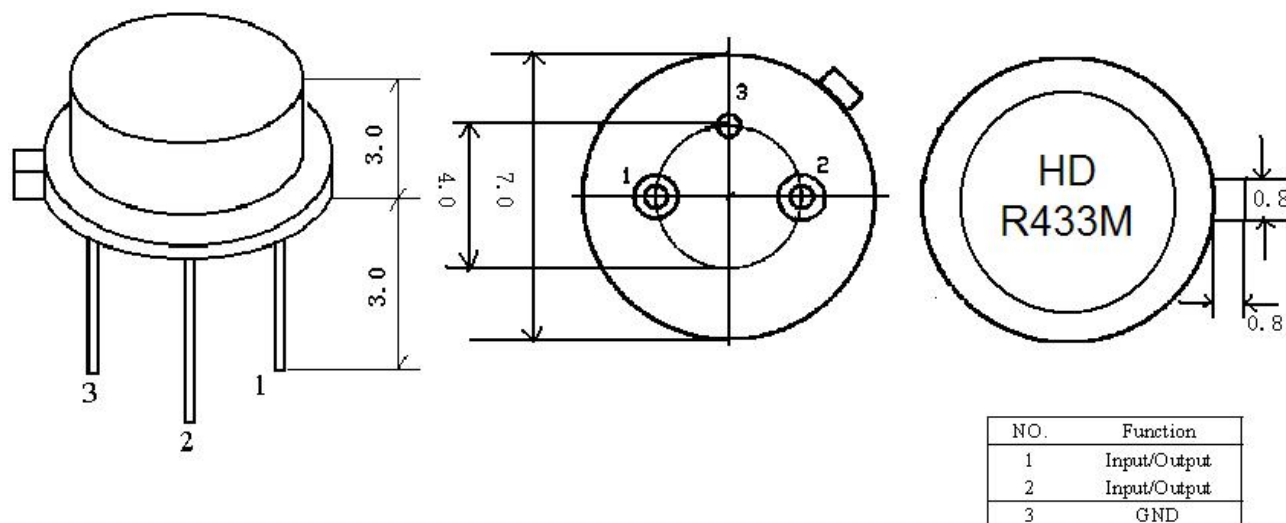
2.2 Electronic Characteristics

Item	Unites	Minimum	Typical	Maximum	
Center Frequency	MHz	433.845	433.920	433.995	
Insertion Loss	dB		1.5	2.5	
Quality Factor Unload Q		5000	12800		
50 Ω Loaded Q		1000	2000		
Temperature Stability	Turnover Temperature	°C	10	25	40
	Freq.temp.Coefficient	ppm/°C ²		0.032	
Frequency Aging	ppm/yr		<±10		
DC. Insulation Resistance	MΩ	1.0			
RF Equivalent RLC Model	Motional Resistance R1	Ω	19	26	
	Motional Inductance L1	μ H	92.929		
	Motional Capacitance C1	fF	1.4475		
Transducer Static Capacitance	pF		1.95		

3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85 °C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40 °C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -45 °C for 30 minutes. Following by a high temperature of +85 °C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260 °C ± 10 °C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245 °C ± 5 °C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the

specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

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